

1. Installation

1.1 Sizes and Weight

- Sizes: 1,010m(W) X 1,020mm(D) X 1,550mm(H)
(Except for the height of the signal tower)
- Weight: Approximately 450 kg



Objective of the machine:

HR8500IIITW-UV picks a wafer, and peels BG tape applied onto the wafer surface after processing the back grind. After the peeling has completed, the machine puts the wafer into the cassette. It is available for thin wafer.